LNJ953W8CRA

Hight Bright Surface Mounting Chip LED

SV (Side View) -0.5 Type

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	15	mA
Pulse forward current *	I_{FP}	70	mA
Reverse voltage	V_R	5	V
Operating ambient temperature	T_{opr}	–30 to +85	°C
Storage temperature	T_{stg}	–40 to +100	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color

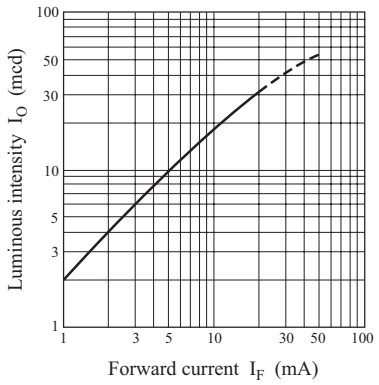
• Blue

■ Electro-Optical Characteristics $T_a = 25°C \pm 3°C$

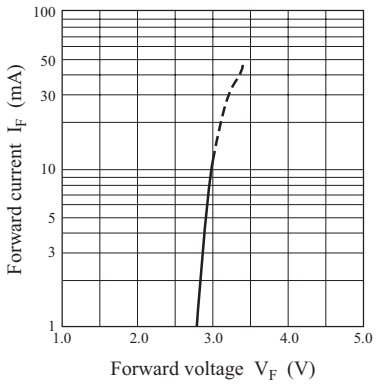
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	I_O	$I_F = 5$ mA	7.0	10.0	34.7	mcd
Reverse current	I_R	$V_R = 5$ V			100	μA
Forward voltage	V_F	$I_F = 5$ mA		2.9	3.2	V
Peak emission wavelength	λ_P	$I_F = 5$ mA		465		nm
Dominant emission wavelength *2	λ_d	$I_F = 5$ mA	462	470	478	nm
Spectral half band width	$\Delta\lambda$	$I_F = 5$ mA		20		nm

Note) *1: Measurement tolerance: ±20%
*2: Measurement tolerance: ±3 nm

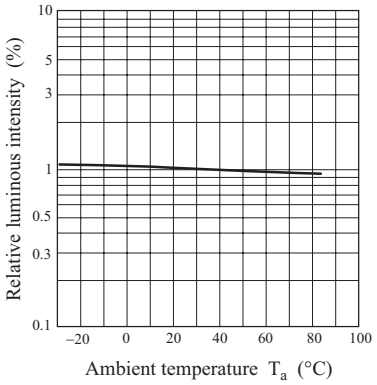
I_O — I_F



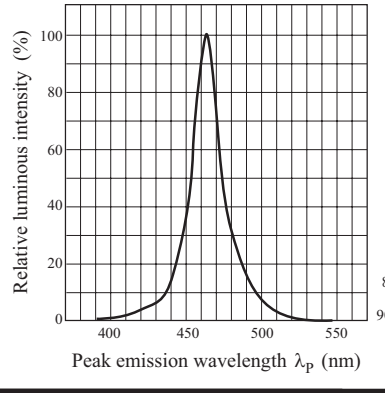
I_F — V_F



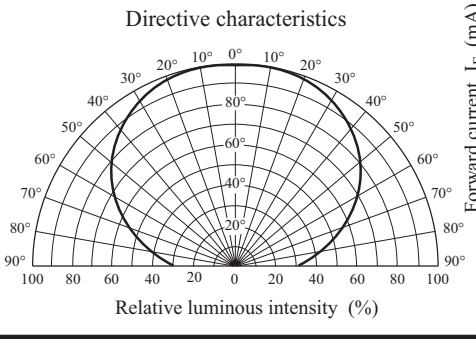
Relative luminous intensity — T_a



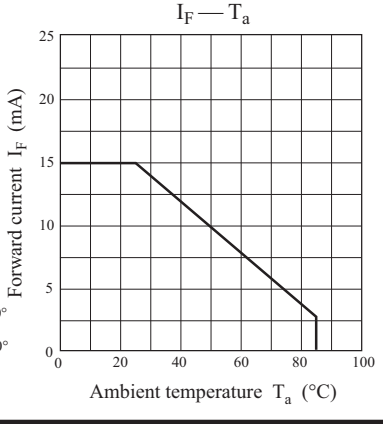
Relative luminous intensity — λ_P



Directive characteristics

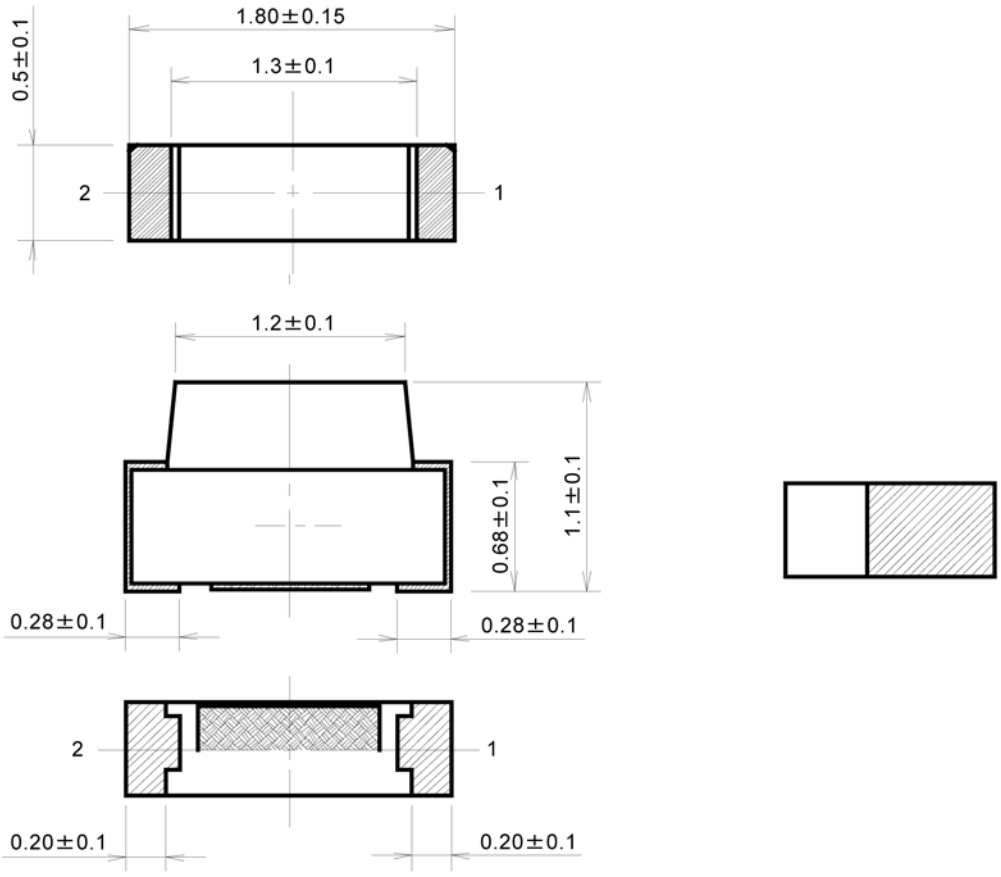


I_F — T_a



■ Package (Unit: mm)

KLTFSN2K5300



- Pin name
  1: Anode
  2: Cathode

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